

ABSTRACT

A semiconductor package is provided that includes: a package substrate; an interposer mounted on the package substrate; a first semiconductor chip mounted on the interposer; a plurality of second semiconductor chips mounted on the interposer to surround at least a portion of the first semiconductor chip; a heat radiation member arranged on the first semiconductor chip and the plurality of second semiconductor chips; and a heat blocking member extending from a portion of the heat radiation member and arranged in at least one space among a first space between the first semiconductor chip and at least one of the plurality of second semiconductor chips and a second space between at least two of the plurality of second semiconductor chips.

FIG. 1